

- NOTES:
- MATERIAL:  
HOUSING - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK  
LATCH - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK  
TERMINAL - COPPER ALLOY
  - FINISHES: TERMINAL PLATING SEE TABLE ON SHEET 5
  - PRODUCT SPECIFICATION: PS-78315-001
  - PACKAGING SPECIFICATION: PRODUCT SHALL BE PACKED IN TRAYS
  - CARD SLOT ACCEPTS 1.27 +/- 0.10MM MODULE THICKNESS (MEASURED FROM PC PADS)
  - MOLEX LOGO, DATE & PART NUMBERS INDICATED ON HOUSING  
DATE CODE SHOULD BE INDICATE AS YYDDDX. 'X' WILL BE THE DIE NO.
  - MODULE SEATING PLANE FROM TOP OF PCB
  - KEEP OUT ZONE RESERVED FOR LATCH

UPT D/C W DIE NO	2015/01/20
EC NO: S2016-1099	2016/07/19
DRWN:CTEH	2016/07/19
CHKD:CGTAN	2016/07/22
APPR:SHLENI	

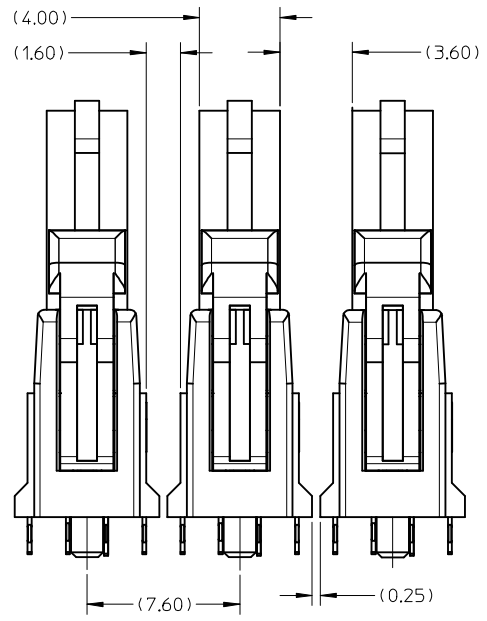
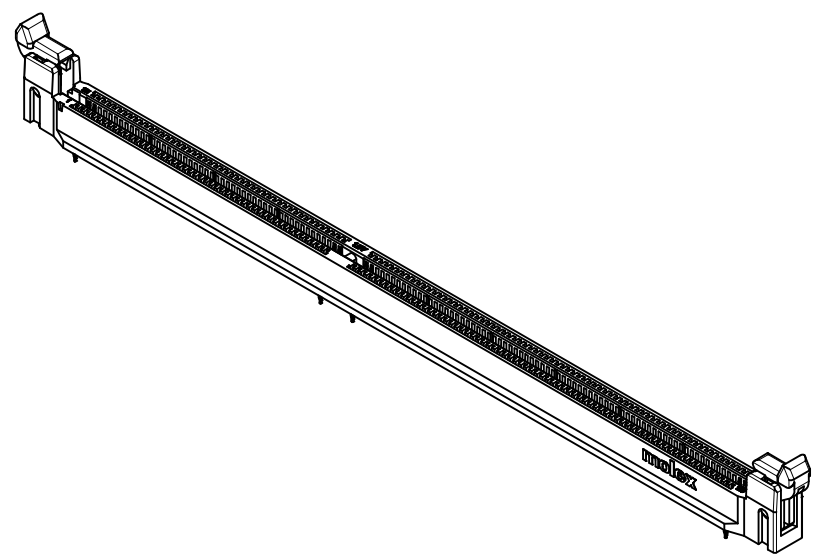
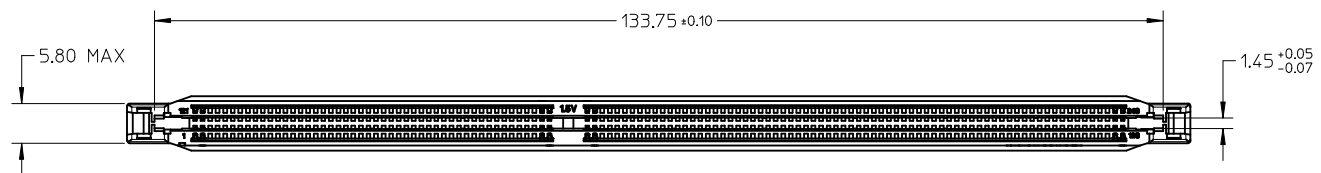
QUALITY SYMBOLS	DESCRIPTION
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$F_G=0$	
$F_B=0$	

GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm INCH
4 PLACES	± --- ± ---
3 PLACES	± --- ± ---
2 PLACES	± 0.20 ± ---
1 PLACE	± --- ± ---
0 PLACE	± --- ± ---
ANGULAR ± 1 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	
MM ONLY	
DRAWN BY	DATE
CMTEO	2008/07/17
CHECKED BY	DATE
CCTEH	2008/07/30
APPROVED BY	DATE
SHLENI	2010/12/15
MATERIAL NO.	
SEE TABLE	

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
NTS	METRIC	
TITLE		
DDR3 DIMM (LSP, VLP) 100MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR		
<b>molex</b>		
DOCUMENT NO.	SHEET NO.	
SD-78315-001	1 OF 6	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

10 9 8 7 6 5 4 3 2 1



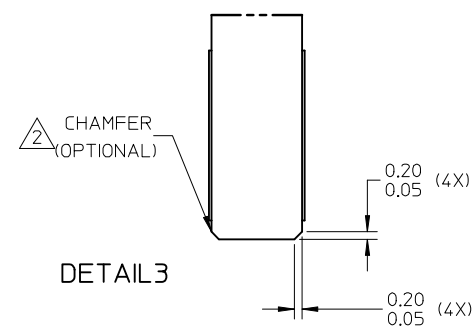
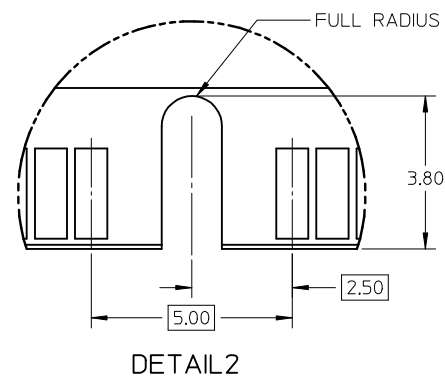
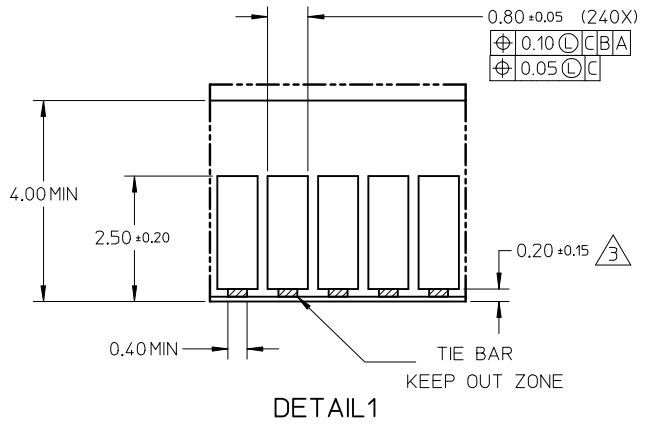
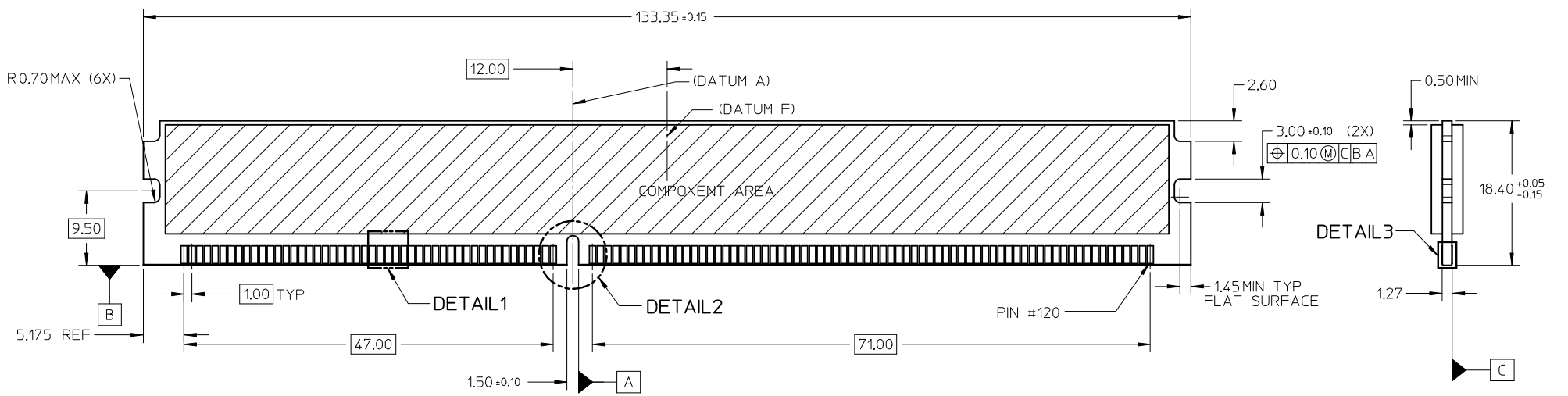
MINIMUM ROW TO ROW SPACING RECOMMENDATION  
(USING 4.00MM MODULE CARD)

UPT D/C W DIE NO EC NO: S2016-1099 DRWN: CCTEH 2015/01/20 CHKD: CGTAN 2016/07/19 APPR: SHLENI 2016/07/22	DESCRIPTION REV A3	QUALITY SYMBOLS $\nabla_{\sigma} = 0$ $\nabla_{\sigma} = 0$ $\nabla_{\sigma} = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
			mm	INCH	DRAWN BY CMTEO	DATE 2008/07/17	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR					
			4 PLACES	± ---	± ---	CHECKED BY CCTEH	DATE 2008/07/30	<b>molex</b> DOCUMENT NO. SD-78315-001 SHEET NO. 2 OF 6				
			3 PLACES	± ---	± ---	APPROVED BY SHLENI	DATE 2010/12/15					
			2 PLACES	± 0.20	± ---	MATERIAL NO.		SEE TABLE				
1 PLACE	± ---	± ---	ANGULAR ± 1 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							
0 PLACE	± ---	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS									

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10 9 8 7 6 5 4 3 2 1

009MODULE CARD  
 DDR3 DUAL INLINE MEMORY MODULE FAMILY 1.00 CONTACT CENTERS  
 (JEDEC MO-269, ISSUE A, 12/05)

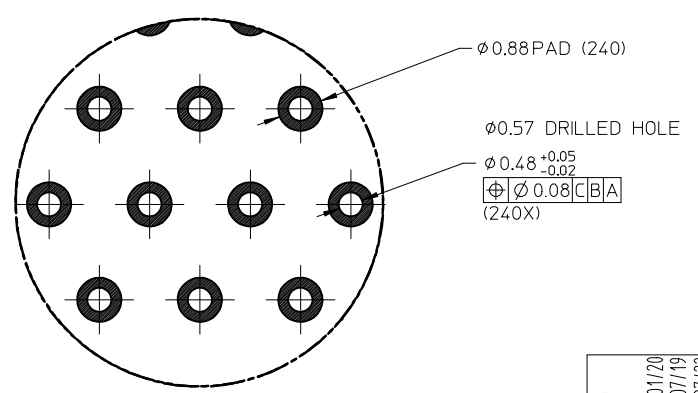
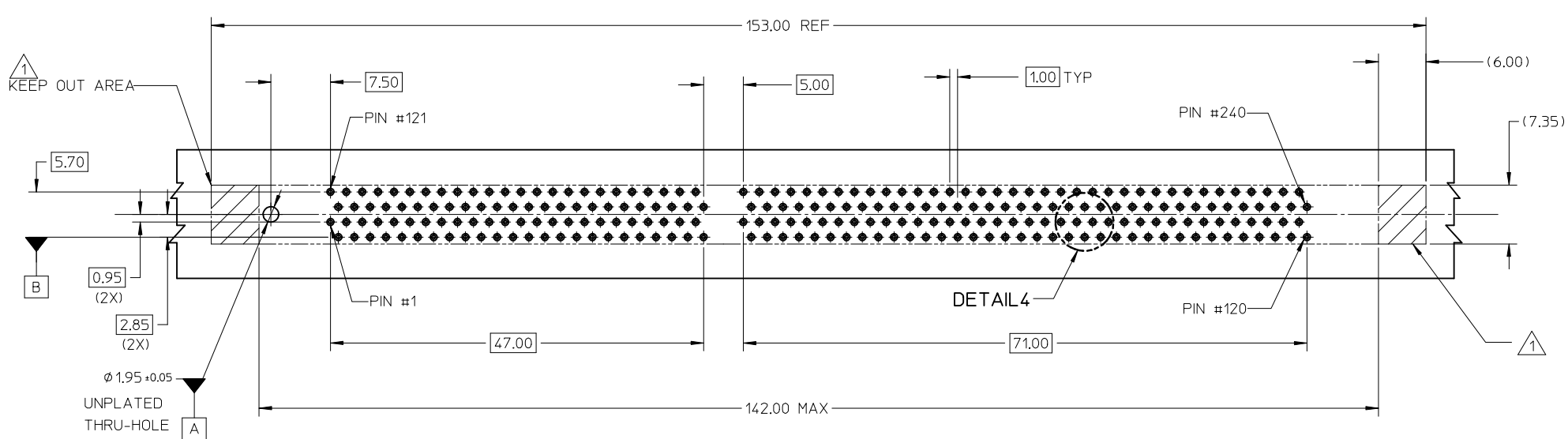


NOTES:  
 1. RECOMMENDED PLATING FOR CONTACT PADS:  
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN OVER 2.00 MICROMETERS NICKEL  
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING OVER 2.00 MICROMETERS NICKEL MUST USE AN ELECTRONIC CONTACT GRADE CORROSIVE BARRIER LUBRICANT  
 2. CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS  
 3. LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS

UPT D/C W DIE NO A3	REV	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
				mm	INCH	MM ONLY		NTS	METRIC		
				4 PLACES	± ---	± ---	DRAWN BY	DATE	TITLE		
				3 PLACES	± ---	± ---	CMTEO	2008/07/17	DDR3 DIMM (LSP, VLP)		
2 PLACES	± 0.20	± ---	CHECKED BY	DATE	1.00MM PITCH, 240 CKTS						
1 PLACE	± ---	± ---	CCTEH	2008/07/30	VERTICAL P/F, LOWLLCR						
0 PLACE	± ---	± ---	APPROVED BY	DATE							
			SHLENI	2010/12/15	DOCUMENT NO.		SD-78315-001				
			MATERIAL NO.		SEE TABLE		SHEET NO.				
			ANGULAR ± 1 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		3 OF 6				

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1



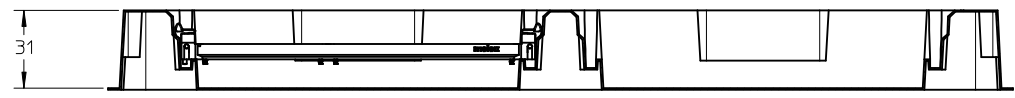
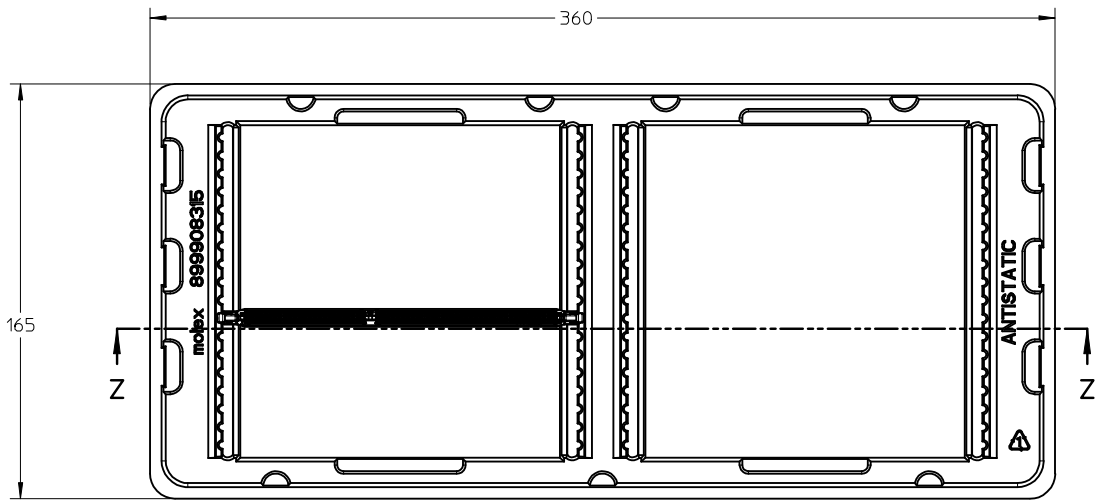
NOTES:  
 1. KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDING LATCH) IS MOUNTED ON THE PCB

UPT D/C W DIE NO EC NO: S2016-1099 DRWN: CCTEH 2015/01/20 CHYK: CGTAN 2016/07/19 APPR: SHLENI 2016/07/22	QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY	DATE	TITLE			
		4 PLACES	± ---	± ---	CMTEO	2008/07/17	DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR			
		3 PLACES	± ---	± ---	CCTEH	2008/07/30				
2 PLACES	± 0.20	± ---	APPROVED BY		DATE	<b>molex</b> SD-78315-001				
1 PLACE	± ---	± ---	SHLENI		2010/12/15					
0 PLACE	± ---	± ---	MATERIAL NO.		DATE	DOCUMENT NO.		SHEET NO.		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			ANGULAR ± 1 °		SEE TABLE		SD-78315-001		4 OF 6	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

VIEW FOR PACKAGING TRAY



SECTION Z-Z

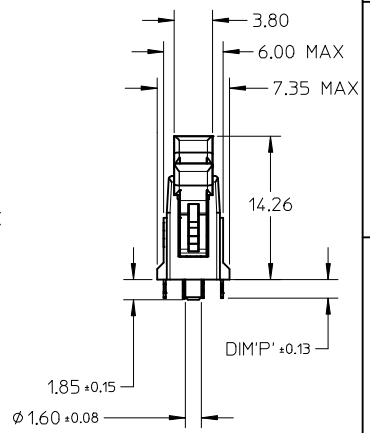
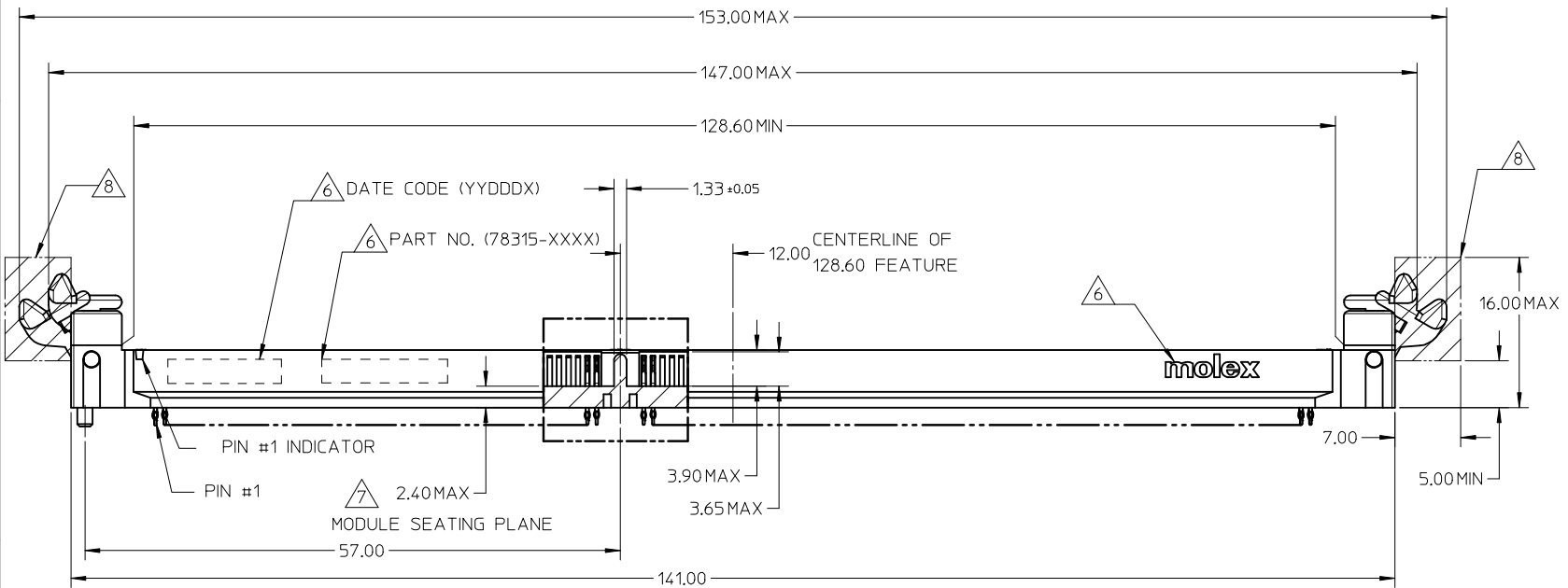
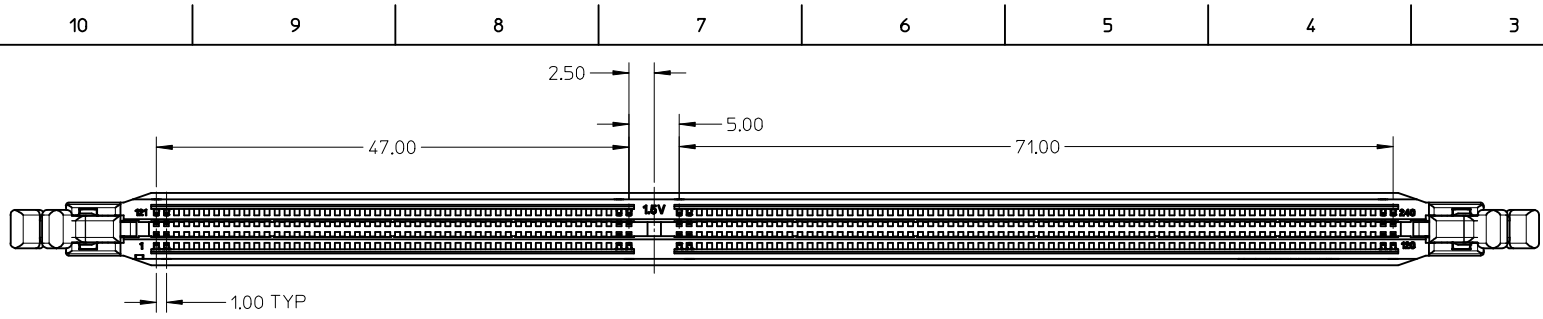
NOTE:  
1. NO. OF CAVITY - 18 X 2 =36

UPT D/C W DIE NO EC NO: S2016-1099 DRW: CCTEH 2015/01/20 CHKD: CGTAN 2016/07/19 APPR: SHLENI 2016/07/22 REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$\nabla_{\sqrt{R}}=0$ $\nabla_{\sqrt{G}}=0$ $\nabla_{\sqrt{F}}=0$	mm	INCH	MM ONLY	NTS	METRIC	
		4 PLACES	± ---	± ---	DRAWN BY	DATE	TITLE
		3 PLACES	± ---	± ---	CMTED	2008/07/17	DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR
	2 PLACES	± 0.20	± ---	CCTEH	2008/07/30		
	1 PLACE	± ---	± ---	SHLENI	2010/12/15	<b>molex</b> SD-78315-001	
	0 PLACE	± ---	± ---				
		ANGULAR ± 1 °		MATERIAL NO.	DOCUMENT NO.		SHEET NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE	SD-78315-001		5 OF 6
A3				SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
				A3			

9 8 7 6 5 4 3 2 1

PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION		LATCH COLOUR	HOUSING COLOUR
				CONTACT AREA	TAIL AREA		
78315-0001	CENTER (1.5V)	1.85	2.40	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN (MATT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	BLACK	BLACK
78315-0051						BLUE	BLUE
78315-0011		2.85	2.60			BLACK	BLACK

UPT D/C W DIE NO EC NO: S2016-1099 DRWN: CCTEH CHKD: CGTAN APPR: SHLENI 2015/01/20 2016/07/19 2016/07/22	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$F_A=0$ $F_G=0$ $F_P=0$	mm    INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± --- 0 PLACE ± --- ± ---	MM ONLY	NTS	METRIC	
	DESCRIPTION	DRAWN BY: CMTEO    DATE: 2008/07/17 CHECKED BY: CCTEH    DATE: 2008/07/30 APPROVED BY: SHLENI    DATE: 2010/12/15	TITLE	DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR		
	REV	ANGULAR ± 1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.	DOCUMENT NO.		
	A3	SEE TABLE	SD-78315-001	SHEET NO. 6 OF 6		



- NOTES:
- MATERIAL:  
HOUSING - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK  
LATCH - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK  
TERMINAL - COPPER ALLOY
  - FINISHES: TERMINAL PLATING SEE TABLE ON SHEET 5
  - PRODUCT SPECIFICATION: PS-78315-001
  - PACKAGING SPECIFICATION: PRODUCT SHALL BE PACKED IN TRAYS
  - CARD SLOT ACCEPTS 1.27 +/- 0.10MM MODULE THICKNESS (MEASURED FROM PC PADS)
  - MOLEX LOGO, DATE & PART NUMBERS INDICATED ON HOUSING  
DATE CODE SHOULD BE INDICATE AS YYDDDX. 'X' WILL BE THE DIE NO.
  - MODULE SEATING PLANE FROM TOP OF PCB
  - KEEP OUT ZONE RESERVED FOR LATCH

UPT D/C W DIE NO	2015/01/20
EC NO: S2016-1099	2016/07/19
DRW:NCCTEH	2016/07/19
CHKD:CGTAN	2016/07/22
APPR:SHLENI	

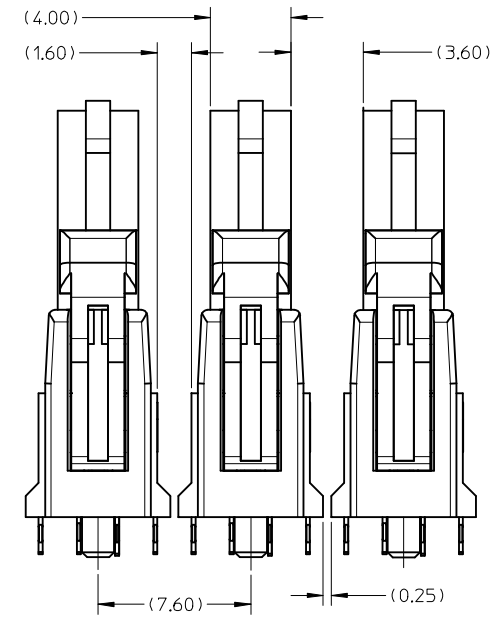
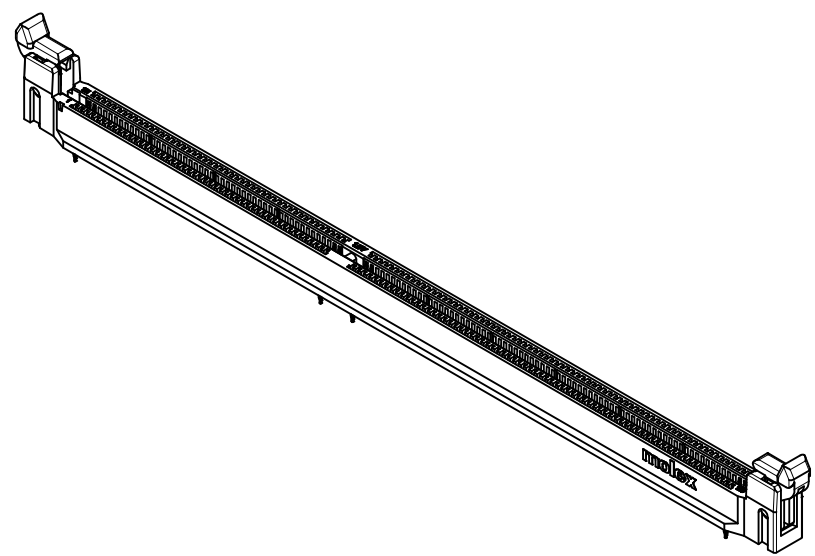
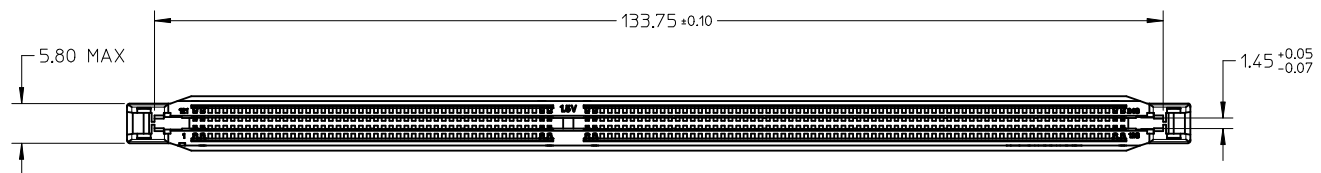
QUALITY SYMBOLS	DESCRIPTION
$F_A=0$	
$F_G=0$	
$F_B=0$	

GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm INCH
4 PLACES	± --- ± ---
3 PLACES	± --- ± ---
2 PLACES	± 0.20 ± ---
1 PLACE	± --- ± ---
0 PLACE	± --- ± ---
ANGULAR ± 1 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE MM ONLY	
DRAWN BY	DATE
CMTEO	2008/07/17
CHECKED BY	DATE
CCTEH	2008/07/30
APPROVED BY	DATE
SHLENI	2010/12/15
MATERIAL NO.	
SEE TABLE	

SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
TITLE		
DDR3 DIMM (LSP, VLP) 100MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR		
<b>molex</b>		
DOCUMENT NO.	SHEET NO.	
SD-78315-001	1 OF 6	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

10 9 8 7 6 5 4 3 2 1



MINIMUM ROW TO ROW SPACING RECOMMENDATION  
(USING 4.00MM MODULE CARD)

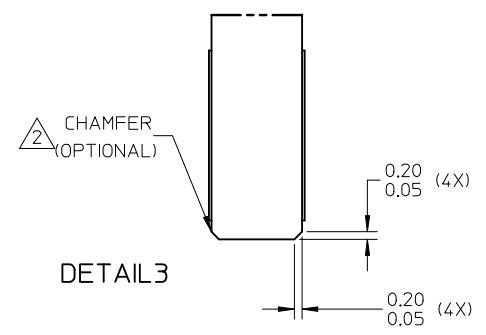
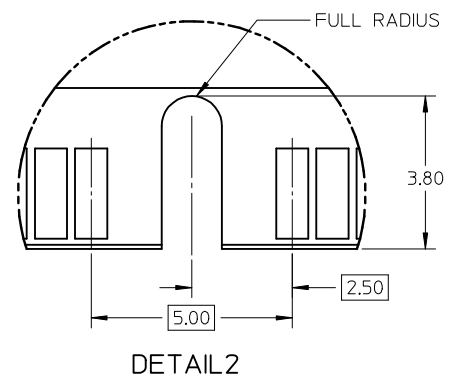
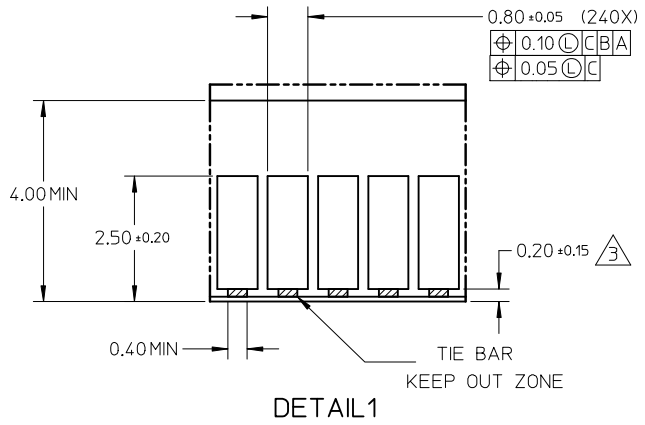
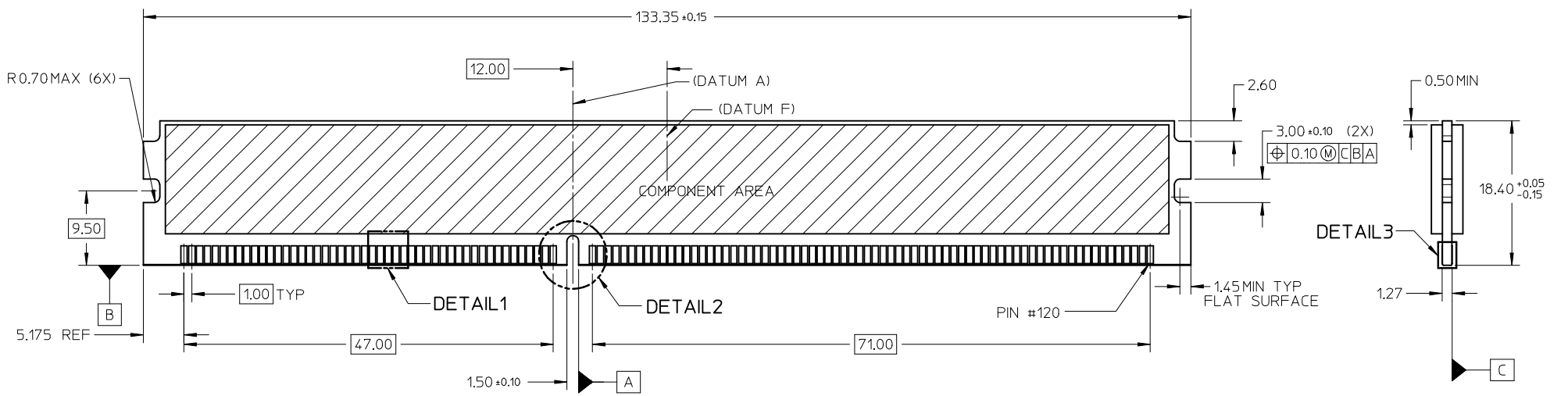
UPT D/C W DIE NO EC NO: S2016-1099 DRWN: CCTEH 2015/01/20 CHKD: CGTAN 2016/07/19 APPR: SHLENI 2016/07/22	QUALITY SYMBOLS $F_s = 0$ $F_G = 0$ $F_P = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY	DATE	TITLE			
		4 PLACES	± ---	± ---	CMTEO	2008/07/17	DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR  <b>molex</b> DOCUMENT NO. SD-78315-001 SHEET NO. 2 OF 6			
		3 PLACES	± ---	± ---	CHECKED BY	DATE				
2 PLACES	± 0.20	± ---	CCTEH	2008/07/30						
1 PLACE	± ---	± ---	APPROVED BY	DATE						
0 PLACE	± ---	± ---	SHLENI	2010/12/15	MATERIAL NO.		SEE TABLE			
ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

9 8 7 6 5 4 3 2 1



10 9 8 7 6 5 4 3 2 1

009MODULE CARD  
 DDR3 DUAL INLINE MEMORY MODULE FAMILY 1.00 CONTACT CENTERS  
 (JEDEC MO-269, ISSUE A, 12/05)

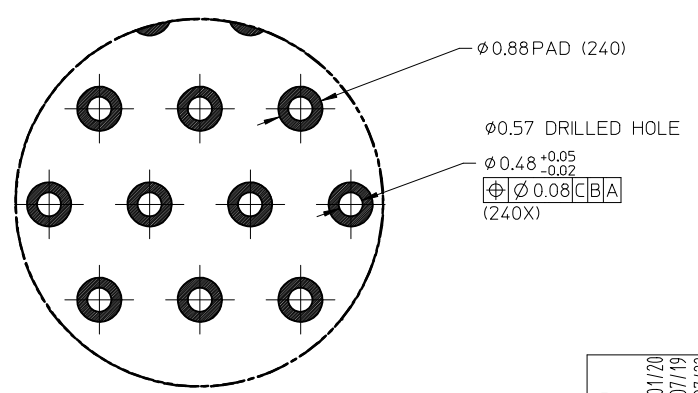
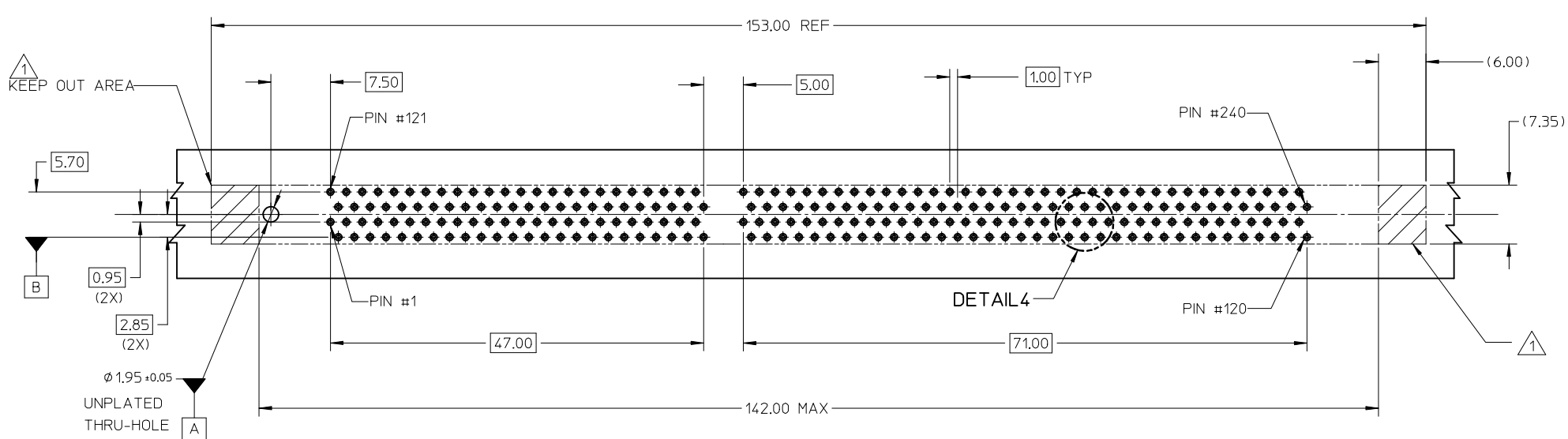


NOTES:  
 1. RECOMMENDED PLATING FOR CONTACT PADS:  
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN  
 OVER 2.00 MICROMETERS NICKEL  
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING  
 OVER 2.00 MICROMETERS NICKEL MUST  
 USE AN ELECTRONIC CONTACT GRADE  
 CORROSIVE BARRIER LUBRICANT  
 2. CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS  
 3. LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE  
 SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS

UPT D/C W DIE NO A3	REV	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
						MM ONLY		NTS	METRIC		
					mm	INCH	DRAWN BY	DATE	TITLE		
				4 PLACES	± ---	± ---	CMTEO	2008/07/17	DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR		
			3 PLACES	± ---	± ---	CCTEH	2008/07/30	molex			
			2 PLACES	± 0.20	± ---	SHLENI	2010/12/15	DOCUMENT NO.		SHEET NO.	
			1 PLACE	± ---	± ---	MATERIAL NO.		SD-78315-001		3 OF 6	
			0 PLACE	± ---	± ---	SEE TABLE					
				ANGULAR ± 1 °		SIZE					
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		A3					
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1



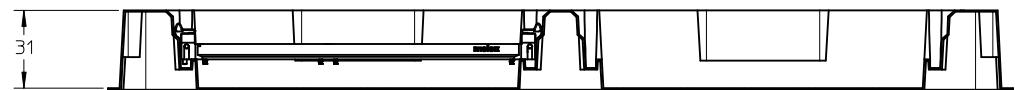
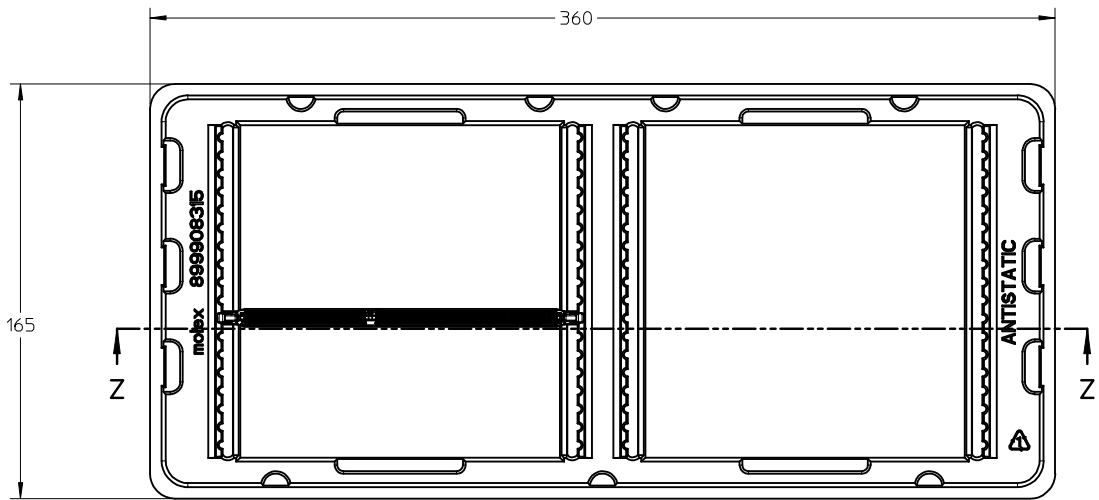
NOTES:  
 1. KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDING LATCH) IS MOUNTED ON THE PCB

UPT D/C W DIE NO EC NO: S2016-1099 DRWN: CCTEH 2015/01/20 CHYK: CGTAN 2016/07/19 APPR: SHLENI 2016/07/22	QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± ---	mm INCH	DRAWN BY CMTEO	DATE 2008/07/17	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR			
		3 PLACES ± --- ± ---	± 0.20 ± ---	CHECKED BY CCTEH	DATE 2008/07/30	MATERIAL NO.			
		2 PLACES ± --- ± ---	± --- ± ---	APPROVED BY SHLENI	DATE 2010/12/15	DOCUMENT NO. SD-78315-001			
1 PLACE ± --- ± ---	± --- ± ---	ANGULAR ± 1 °		SEE TABLE		SHEET NO. 4 OF 6			
0 PLACE ± --- ± ---	± --- ± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

VIEW FOR PACKAGING TRAY



SECTION Z-Z

NOTE:  
1. NO. OF CAVITY - 18 X 2 =36

UPT D/C W DIE NO EC NO: S2016-1099 DRW: CCTEH 2015/01/20 CHKD: CGTAN 2016/07/19 APPR: SHLENI 2016/07/22	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$\nabla_{\sqrt{R}}=0$	mm	INCH	MM ONLY	NTS	METRIC	
	$\nabla_{\sqrt{G}}=0$	4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	DRAWN BY	DATE	TITLE	
	$\nabla_{\sqrt{F}}=0$	2 PLACES ± 0.20 ± ---	1 PLACE ± --- ± ---	CCTEH	2008/07/17	DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR	
	0 PLACE ± --- ± ---	ANGULAR ± 1 °		SHLENI	2010/12/15	molex	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		DOCUMENT NO.		SHEET NO.
A3			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		5 OF 6

9 8 7 6 5 4 3 2 1

PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION		LATCH COLOUR	HOUSING COLOUR
				CONTACT AREA	TAIL AREA		
78315-0001	CENTER (1.5V)	1.85	2.40	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN (MATT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	BLACK	BLACK
78315-0051						BLUE	BLUE
78315-0011		2.85	2.60			BLACK	BLACK

UPT D/C W DIE NO EC NO: S2016-1099 DRWN: CCTEH CHKD: CGTAN APPR: SHLENI 2015/01/20 2016/07/19 2016/07/22	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$F_A=0$ $F_G=0$ $F_P=0$	mm    INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± --- 0 PLACE ± --- ± ---	MM ONLY	NTS	METRIC	
	DESCRIPTION	DRAWN BY: CMTEO    DATE: 2008/07/17 CHECKED BY: CCTEH    DATE: 2008/07/30 APPROVED BY: SHLENI    DATE: 2010/12/15	TITLE: DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR			
	REV	ANGULAR ± 1 °	MATERIAL NO.	DOCUMENT NO.		SHEET NO.
	A3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	SD-78315-001		6 OF 6

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION